

## Mounting Accessories for Board



## Mounting Accessories for Heatsinks HS1, HS2 \& HS3 <br> $\square$ <br> M1, M2, M3 are NOT needed when TO-220-Flatpack package is used

You should delete the nylon screws/standoffs and/or the
bumpons as needed for your design (or substitute other parts
from Hardware.Intiib). Bumpons are cheaper, but provide les from Hard
clearance.

Deleting anything else from this page may result in your EVM
submission being rejected (until you add them back)
Update the Label Text in the Label Table as needed for each Assembly Varian

You can delete this note too

PBL1
$\frac{\text { PCB Label }}{\text { Size: } 0.65^{5} \times 0.20 "}$


| Label Table |  |
| :---: | :---: |
| Variant | Label Text |
| 001 | Changeme! |
| 002 | ChangeMe! |
|  |  |
|  |  |
|  |  |
|  |  |
|  |  |

$\frac{\mathrm{zz2}}{\frac{\mathrm{Z} \text { Assembly Note }}{\text { These assemblies are ESD sensitive, ESD precautions shall be observed. }} \text {. }}$
$\frac{\mathrm{Zz3}}{\frac{\text { Assembly }}{\text { Thesete }}}$



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